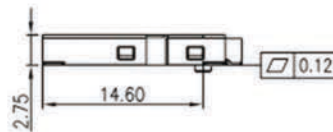
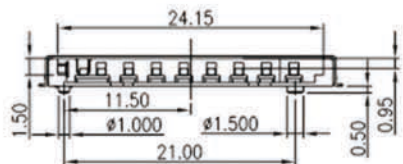
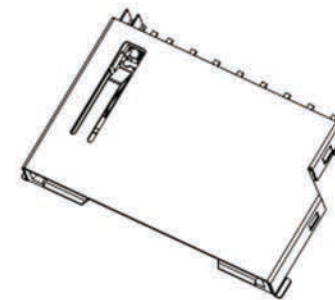
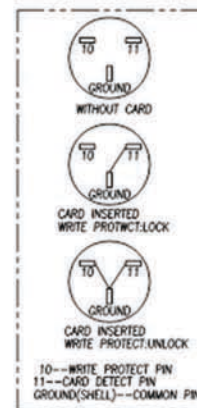


P.C.B Layout



SD CARD PIN DESIGN

Pin No.	Name	Description
1#	CD/DAT3	Card detect/Data I/O
2#	CMD	Command
3#	VSS1	Ground
4#	VDD	Power
5#	CLK	Clock
6#	VSS2	Ground
7#	DAT0	Data I/O
8#	DAT1	Data I/O
9#	DAT2	Data I/O



NOTES:

- MATERIAL
HOUSING: HIGH TEMPERATURE THERMOPLASTIC (LCP)
CONTACT: COPPER ALLOY (C5191 ± 0.20).
SHELL: COPPER ALLOY (SUS430 ± 0.20).
- PLATING
CONTACT AREA: GOLD PLATED OVER Ni.
SOLDER TAIL: 100 μ m MIN Sn PLATED OVER Ni.
SPEC SEE ORDERING INFORMATION
SHELL SOLDER AREA: GOLD PLATED OVER Ni.
- RATING
CURRENT RATING: 0.5A
VOLTAGE RATING: 250V_{RM}
OPERATING TEMPERATURE: -25° C~90° C
- SPECIFICATION
CONTACT RESISTANCE: 100m Ω Max
DIELECTRIC WITHSTANDING VOLTAGE: 500VAC
INSULATION RESISTANCE: 100M Ω Min
INSERTION FORCE: 40N MAX
SEPARATION FORCE: 2N MIN.

UNITS: mm	CSCONN	SHENZHEN CSCONN PRECISE ELECTRONICS CO.,LTD			
GENERAL TOLERANCE	PART NO.(INTENDED USE) CSD276166275	TITLE: SD CARD 短体			
X. * $\pm 5^\circ$ 0.X ± 0.3	APPD:	DWG NO. SD			
X.1 $\pm 2^\circ$ 0.XX ± 0.2	CHKD: Skila		SCALE	SHEET	REV
XX. $\pm 1^\circ$ 0.XXX ± 0.1	DR: Kitty		1:1	1 OF 1	A
XXX. $\pm 0.5^\circ$					